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2A, 100V - 200V Surface Mount Ultra Fast Rectifier

FEATURES

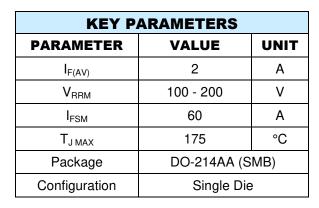
- Glass passivated junction chip
- Ideal for automated placement
- Low profile package
- Ultra fast recovery time for high efficiency
- Compliant to RoHS Directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21

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- Switching mode power supply (SMPS)
- Adapters
- Lighting application
- Converter

MECHANICAL DATA

- Case: DO-214AA (SMB)
- Molding compound meets UL 94V-0 flammability rating
- Part no. with suffix "H" means AEC-Q101 qualified
- Packing code with suffix "G" means green compound (halogen-free)
- Moisture sensitivity level: level 1, per J-STD-020
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: As marked
- Weight: 0.09 g (approximately)







DO-214AA (SMB)

PARAMETER	SYMBOL	ESH2B	ESH2C	ESH2D	UNIT
Marking code on the device		ESH2B	ESH2C	ESH2D	
Repetitive peak reverse voltage	V_{RRM}	100	150	200	V
Reverse voltage, total rms value	$V_{R(RMS)}$	70	105	140	V
Maximum DC blocking voltage	V_{DC}	100	150	200	V
Forward current	I _{F(AV)}		2	•	Α
Surge peak forward current, 8.3 ms single half sine-wave superimposed on rated load per diode	I _{FSM}		60		Α
Junction temperature T _J - 55 to +175			°C		
Storage temperature T _{STG} - 55 to		- 55 to +175		°C	

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THERMAL PERFORMANCE					
PARAMETER	SYMBOL	LIMIT	UNIT		
Junction-to-lead thermal resistance	$R_{\Theta JL}$	20	°C/W		
Junction-to-ambient thermal resistance	$R_{\Theta JA}$	75	°C/W		

ELECTRICAL SPECIFICATIONS (T _A = 25°C unless otherwise noted)					
PARAMETER	CONDITIONS	SYMBOL	TYP	МАХ	UNIT
Forward voltage per diode (1)	$I_F = 2A, T_J = 25^{\circ}C$	V _F	-	0.9	V
Decrees a support Quarted V and display (2)	T _J = 25°C		-	2	μΑ
Reverse current @ rated V _R per diode (2)	T _J = 125°C	I _R	-	50	μΑ
Junction capacitance	1 MHz, V _R =4.0V	CJ	25	-	рF
Payara racayary tima	I _F =0.5A ,I _R =1.0A I _{RR} =0.25A	+	-	20	ns
Reverse recovery time	I _{RR} =0.25A	t _{rr}			

Notes:

- 1. Pulse test with PW=0.3 ms
- 2. Pulse test with PW=30 ms

RDERING INFORMATION							
PART NO.	PART NO. SUFFIX	PACKING CODE	PACKING CODE SUFFIX(*)	PACKAGE	PACKING		
ESH2x (Note 1)	Н	R5	G	SMB	850 / 7" Plastic reel		
		R4		SMB	3,000 / 13" Paper reel		
		M4		SMB	3,000 / 13" Plastic reel		

Note:

- 1. "x" defines voltage from 100V (ESH2B) to 200V (ESH2D)
- *: Optional available

EXAMPLE P/N						
EXAMPLE P/N	PART NO.	PART NO. SUFFIX	PACKING CODE	PACKING CODE SUFFIX	DESCRIPTION	
ESH2DHR5G	ESH2D	Н	R5	G	AEC-Q101 qualified Green compound	



CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

Fig.1 Forward Current Derating Curve

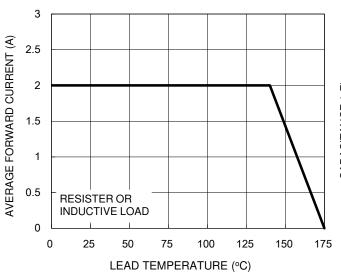


Fig.2 Typical Junction Capacitance

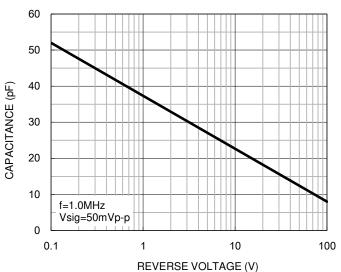


Fig.3 Typical Reverse Characteristics

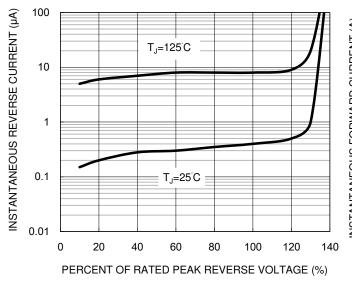
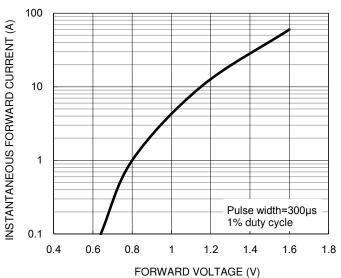


Fig.4 Typical Forward Characteristics



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CHARACTERISTICS CURVES

(T_A = 25°C unless otherwise noted)

Fig.5 Maximum Non-repetitive Forward Surge Current

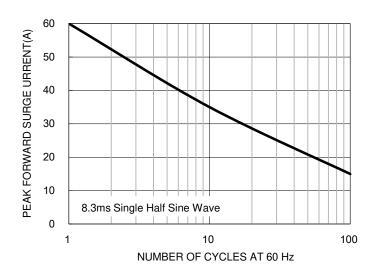
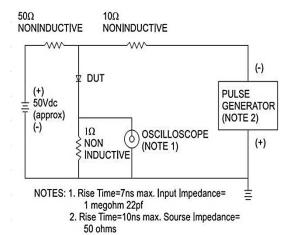
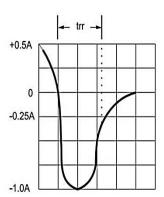


Fig.6 Reverse Recovery Time Characteristic And Test Circuit Diagram

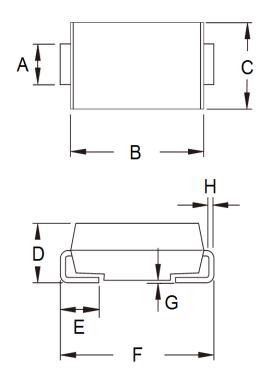






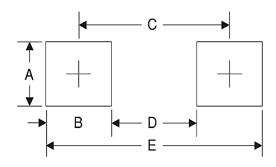
PACKAGE OUTLINE DIMENSIONS

DO-214AA (SMB)



DIM.	Unit	(mm)	Unit (inch)		
DIW.	Min	Max	Min	Max	
Α	1.95	2.20	0.077	0.087	
В	4.05	4.60	0.159	0.181	
С	3.30	3.95	0.130	0.156	
D	1.95	2.65	0.077	0.104	
Е	0.75	1.60	0.030	0.063	
F	5.10	5.60	0.201	0.220	
G	0.05	0.20	0.002	0.008	
Н	0.15	0.31	0.006	0.012	

SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
A	2.3	0.091
В	2.5	0.098
С	4.3	0.169
D	1.8	0.071
E	6.8	0.268

MARKING DIAGRAM



= Marking Code= Green Compound P/N G YW = Date Code = Factory Code



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